# Single/Dual-Channel High-Voltage Protection T/R Switch 

## Features

- Up to $\pm 100 \mathrm{~V}$ Input Voltage Protection
- Low On-Resistance, $15 \Omega$ Typical
- Fast-Switching Speed
- Effective Simple Two-Terminal Device
- No External Supplies Needed


## Applications

- Medical Ultrasound Imaging
- Non-Destructive Testing Applications
- Fast Resettable Fuses
- High-Side Switches
- Data Acquisition


## General Description

The MD0100 is a high-voltage, two-terminal, bi-directional, current-limiting protection device. The two terminals are interchangeable. It is designed to protect a low-noise receiver from high-voltage transmit pulses in ultrasound applications and is commonly referred to as a transmit-and-receive (T/R) switch.
The MD0100 can be considered as a normally closed switch with a typical switch resistance of $15 \Omega$ that allows small signals to pass. When the voltage drop across the two terminals exceeds a nominal value of $\pm 2 \mathrm{~V}$, the device turns off. In the OFF state, the MD0100 can withstand up to $\pm 100 \mathrm{~V}$ across its terminals. A small amount of current (typically $200 \mu \mathrm{~A}$ ) is allowed to flow through.
The applications for the MD0100 are not limited to just ultrasound. It can also be used as resettable fuses to protect power lines, output short-circuit protection and data acquisition. The MD0100 is available in an SOT-89 package as a single-channel device, as well as in a $4 \mathrm{~mm} \times 4 \mathrm{~mm}$ 8-lead DFN package as a dual-channel device.

## Package Types



See Table 2-1 and Table 2-2 for pin information.

MD0100

Functional Block Diagram


## Typical Application Circuit



## MD0100

### 1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings $\dagger$Differential Voltage, $\mathrm{V}_{\mathrm{A}-\mathrm{B}}$
$\qquad$ .0 V to +110 V
Maximum Junction Temperature, $T_{J}$ ..... $+125^{\circ} \mathrm{C}$
Storage Temperature, $\mathrm{T}_{\mathrm{S}}$ ..... $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Power Dissipation:
3-lead SOT-89 (Note 1, Note 2) ..... 1.6W
8 -lead DFN (Note 1, Note 2) ..... 1.67W
$\dagger$ Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note 1: Mounted on an FR4 board, $25 \mathrm{~mm} \times 25 \mathrm{~mm} \times 1.57 \mathrm{~mm}$
2: The maximum power dissipation is per die. A package has two dies.

## DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_{J}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| Parameter | Sym. | Min. | Typ. | Max. | Unit | Conditions |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| Maximum Differential Input Voltage <br> from A to B | $\mathrm{V}_{\mathrm{A}-\mathrm{B}}$ | $\pm 100$ | - | - | V | $\mathrm{I}_{\mathrm{A}-\mathrm{B}}= \pm 500 \mu \mathrm{~A}$ |
| Switch-On Resistance from A to B | $\mathrm{R}_{\mathrm{SW}}$ | - | 15 | - | $\Omega$ | $\mathrm{I}_{\mathrm{A}-\mathrm{B}}= \pm 5 \mathrm{~mA}$ |
| $\mathrm{~V}_{\mathrm{A}-\mathrm{B}}$ Trip Point to Turn Off | $\mathrm{V}_{\text {TRIP }}$ | - | $\pm 1$ | $\pm 2$ | V |  |
| Switch Turn-Off Voltage | $\mathrm{V}_{\text {OFF }}$ | - | $\pm 2$ | - | V | $\mathrm{I}_{\mathrm{A}-\mathrm{B}}= \pm 1 \mathrm{~mA}$ |
| Switch-Off Current | $\mathrm{I}_{\mathrm{A}-\mathrm{B}(\mathrm{OFF})}$ | - | $\pm 200$ | $\pm 300$ | $\mu \mathrm{~A}$ | $\mathrm{~V}_{\mathrm{A}-\mathrm{B}}= \pm 100 \mathrm{~V}$ |

## AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_{J}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| Parameter | Sym. | Min. | Typ. | Max. | Unit | Conditions |
| :--- | :---: | :---: | :---: | :---: | :---: | :--- |
| Peak Switching Current | $\mathrm{I}_{\text {PEAK }}$ | - | $\pm 60$ | - | mA | See Figure 3-8. |
| Turn-Off Time | $\mathrm{T}_{\mathrm{OFF}}$ | - | - | 20 | ns | See Figure 3-2, Figure 3-3 <br> and Figure 3-4. |
| Turn-On Time | $\mathrm{T}_{\mathrm{ON}}$ | - | - | 20 | ns | See Figure 3-5, Figure 3-6 <br> and Figure 3-7. |
| Switch-On Capacitance from A to B | $\mathrm{C}_{\mathrm{SW}(\mathrm{ON})}$ | - | 21 | - | pF | $\mathrm{SW}=\mathrm{ON}$ |
| Switch-Off Capacitance from A to B | $\mathrm{C}_{\text {SW(OFF) }}$ | - | 15 | - | pF | $\mathrm{V}_{\mathrm{SW}}=25 \mathrm{~V}$ |
| Small Signal Bandwidth | BW | - | 100 | - | MHz | $\mathrm{R}_{\mathrm{LOAD}}=50 \Omega$ |

## TEMPERATURE SPECIFICATIONS

| Parameter | Sym. | Min. | Typ. | Max. | Unit | Conditions |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| TEMPERATURE RANGE |  |  |  |  |  |  |
| Operating Junction Temperature | $\mathrm{T}_{\mathrm{J}}$ | -40 | - | +125 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage Temperature | $\mathrm{T}_{\mathrm{S}}$ | -65 | - | +150 | ${ }^{\circ} \mathrm{C}$ |  |
| PACKAGE THERMAL RESISTANCE |  |  |  |  |  |  |
| 3-lead SOT-89 | $\theta_{\mathrm{JA}}$ | - | 133 | - | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ | Note 1 |
| 8-lead DFN | $\theta_{\mathrm{JA}}$ | - | 44 | - | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |  |

Note 1: 4-inch-x-4.5-inch JEDEC 2s2p PCB

## Typical I-V Characteristics


2.0 PIN DESCRIPTION

The functional descriptions for the pins of MD0100 are listed in Table 2-1 and Table 2-2. See Package Types for the location of pins.

TABLE 2-1: 3-LEAD SOT-89 PIN FUNCTION TABLE

| Pin Number | Pin Name | Description |
| :---: | :---: | :--- |
| 1 | A | Switch Terminal A |
| 2 | COM | Do not connect. |
| 3 | B | Switch Terminal B |

TABLE 2-2: 8-LEAD DFN PIN FUNCTION TABLE

| Pin Number | Pin Name | Description |
| :---: | :---: | :--- |
| 1 | A1 | Switch Terminal A1 |
| 2 | B1 | Switch Terminal B1 |
| 3 | A2 | Switch Terminal A2 |
| 4 | B2 | Switch Terminal B2 |
| 5,6, and <br> Heat Slug 2 | COM2 | Do not connect. |
| 7, 8, and <br> Heat Slug 1 | COM1 | Do not connect. |

### 3.0 DETAILED DESCRIPTION

The MD0100 can be considered as a normally closed switch controlled by a built-in control circuit. (See Functional Block Diagram.) The switch control circuit monitors the voltage drop between Terminal A and Terminal $B$. If the voltage difference is greater than $\pm 2 \mathrm{~V}$, the $T / R$ switch will be opened. Once in the Open state, there is a small amount of current flowing through the T/R switch ( 200 uA ) to detect if high voltage is still present. The T/R switch will not close until the voltage between Terminal A and Terminal B drops within $\pm 2 \mathrm{~V}$. A pair of back-to-back diodes, from Terminal B (if it is connected to the receiver side) to ground is needed to complete the circuit and allow the peak current (about 60 mA ) to flow through the switch. If the diodes are not present, there is no current path and the voltage drop across Terminal A and B will be less than $\pm 2 \mathrm{~V}$. As a result, the switch will remain in the ON position.

The other purpose of the diodes is to clamp voltage spikes to $\pm 0.7 \mathrm{~V}$ during transmitting and receiving periods. Low-voltage diodes with low reverse recovery time and low junction capacitances (like BAV99T) should be used.

### 3.1 On Resistance

When the voltage between Terminal A and Terminal B is within $\pm 2 \mathrm{~V}$, the switch is ON and the $\mathrm{R}_{\mathrm{ON}}$ is typically $15 \Omega$. Once the voltage between Terminal $A$ and Terminal B is greater than $\pm 2 \mathrm{~V}$, the switch will be OFF and prevent high-voltage pulses from passing through to the receiver and damaging it.
The MD0100 does not require any power supply. There are only two active pins: the first connects to the transmitter side and the second connects to the receiver side.

### 3.2 Switch Capacitance

The typical switch-on capacitance $\mathrm{CSW}_{(\mathrm{ON})}$ is 21 pF . This is measured from $A$ to $B$ or $B$ to $A$ when the switch is turned on.

The switch-off capacitance is a function of the voltage across the T/R switch. The $\mathrm{C}_{\mathrm{SW} \text { (OFF) }}$ is about 12 pF to 19 pF for 10 V to 100 V of transmit voltage. Refer to Figure 3-1 for the $\mathrm{C}-\mathrm{V}$ curve of $\mathrm{C}_{\mathrm{SW}}$ (OFF).


FIGURE 3-1: $\quad C_{S W(O F F)}$ vs. $V_{S W}$.

## $3.3 \quad \mathrm{~T}_{\mathrm{ON}}$ and $\mathrm{T}_{\text {OFF }}$ Time

The $\mathrm{T}_{\mathrm{ON}}$ and $\mathrm{T}_{\text {OFF }}$ of the MD0100 are less than 20 ns , which provides a quick transition between the Transmit and Receive modes. $\mathrm{T}_{\text {ON }}$ and $\mathrm{T}_{\text {OFF }}$ times are proportional to the rise and fall times of the transmit pulses. The $T_{\text {OFF }}$ and $T_{\text {ON }}$ setups are shown in Figure 3-2 and Figure 3-5, respectively.


FIGURE 3-2: $\quad$ Test Setup for $T_{\text {OFF. }}$


FIGURE 3-3: $\quad T_{\text {OFF }}$ Timing Diagram.


FIGURE 3-4: $\quad T_{\text {OFF }}$ at $V_{A}=10 \mathrm{~V}$.
Figure 3-4 shows the actual waveform and measurement of $T_{\text {OFF. }} T_{\text {OFF }}$ is measured from 2 V of $\mathrm{V}_{\mathrm{A}}$ to $10 \%$ of $\mathrm{V}_{\mathrm{B}}$. From the above waveform, $\mathrm{T}_{\text {OFF }}$ is 11 ns .


FIGURE 3-5: $\quad$ Test Setup for $T_{O N}$.


FIGURE 3-6: $\quad T_{O N}$ Timing Diagram.


FIGURE 3-7: $\quad T_{O N}$ at $V_{A}=10 \mathrm{~V}$.
Figure 3-7 illustrates the actual waveform and measurement of $\mathrm{T}_{\mathrm{ON}}$. $\mathrm{T}_{\mathrm{ON}}$ is measured from 2 V of $\mathrm{V}_{\mathrm{A}}$ to 1 V of $\mathrm{V}_{\mathrm{B}}$. From the above waveform, $\mathrm{T}_{\mathrm{ON}}$ is 6.6 ns .


FIGURE 3-8: $\quad$ Test Setup for $I_{\text {PEAK }}$.


FIGURE 3-9: Test Setup for Waveforms in
Figure 3-10 and Figure 3-11.
Figure 3-10 shows the waveforms of $\mathrm{V}_{\mathrm{A}}$ and $\mathrm{V}_{\mathrm{B}}$ for the test circuit in Figure 3-9. There is a small bump of about 0.5 V at the tail of the $\mathrm{V}_{\mathrm{B}}$ signal because the transmit signal falls into the $\pm 2 \mathrm{~V}$ range, and the MD0100 turns back on again. Figure 3-11 illustrates the same waveforms with both $\mathrm{V}_{\mathrm{A}}$ and $\mathrm{V}_{\mathrm{B}}$ shown with same voltage scale of $2 \mathrm{~V} /$ div.


FIGURE 3-10: Typical Waveform A.


FIGURE 3-11: Typical Waveform B.

### 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

## 3-lead SOT-89



8-lead DFN


## Example



Example
MD0100
K6
(3)1819

- 483

Legend: $X X \ldots$...X Product Code or Customer-specific information
$Y \quad$ Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code
(e3) Pb-free JEDEC ${ }^{\circledR}$ designator for Matte Tin (Sn)

* This package is Pb -free. The Pb -free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

## 3-Lead TO-243AA (SOT-89) Package Outline (N8)



Top View


Side View

Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

| Symbol |  | A | b | b1 | C | D | D1 | E | E1 | e | e1 | H | L |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dimensions (mm) | MIN | 1.40 | 0.44 | 0.36 | 0.35 | 4.40 | 1.62 | 2.29 | $2.00^{+}$ | $\begin{aligned} & 1.50 \\ & \text { BSC } \end{aligned}$ | $\begin{aligned} & 3.00 \\ & \text { BSC } \end{aligned}$ | 3.94 | $0.73{ }^{+}$ |
|  | NOM | - | - | - | - | - | - | - | - |  |  | - | - |
|  | MAX | 1.60 | 0.56 | 0.48 | 0.44 | 4.60 | 1.83 | 2.60 | 2.29 |  |  | 4.25 | 1.20 |

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.
$\dagger$ This dimension differs from the JEDEC drawing
Drawings not to scale.

## 8-Lead DFN Package Outline (K6)

## $4.00 \times 4.00 \mathrm{~mm}$ body, 1.00 mm height (max), 1.00 mm pitch (dual pad)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.


Drawings not to scale

## APPENDIX A: REVISION HISTORY

## Revision A (October 2018)

- Converted Supertex Doc\# DSFP-MD0100 to Microchip DS20005738A
- Changed the power dissipation value of 8-lead DFN from "1.1W" to "1.67W"
- Changed Note 1 to " 4 -inch-x-4.5-inch JEDEC 2s2p PCB"
- Changed the package marking format
- Changed the quantity of the 8-lead DFN K6 package from 3000/Reel to 3300/Reel
- Changed the "3-lead TO-243AA (SOT-89)" package marking to "3-lead SOT-89"
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM
To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

| $\frac{\text { PART NO. }}{\text { Device }}$ | $\frac{X X}{\text { Padkage }}$ Options |  | Examples: a) MD0100N8-G: | Single-Channel High-Voltage Protection T/R Switch, 3-lead SOT89, |
| :---: | :---: | :---: | :---: | :---: |
| Devices: | MD0100 = MD0100D = | Single-Channel High-Voltage Protection T/R Switch, Single Channel <br> Dual-Channel High-Voltage Protection T/R Switch | b) MD0100DK6G: | Dual-Channel High-Voltage Protection T/R Switch, 8-lead (4×4) VDFN, 3300/Reel |
| Packages: | N 8 $=$ <br> K 6 $=$ | 3-lead SOT89 (for single channel only) <br> 8 -lead (4x4) VDFN (for dual channel only) |  |  |
| Environmental: | G = | Lead (Pb)-free/RoHS-compliant Package |  |  |
| Media Type: | $\begin{array}{ll} \text { (blank) } & = \\ \text { (blank) } & = \end{array}$ | 2000/Reel for an N8 Package 3300/Reel for a K6 Package |  |  |

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